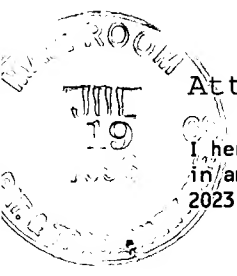


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Attorney Docket No. 95-553-US

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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

GROUP 3200

Title of the Invention:

PROBE CARD ASSEMBLY AND KIT, AND METHODS OF USING SAME

Inventors: ELDRIDGE, et al.

Filing Date: November 9, 1995

Serial Number: 08/554,902

SUPPLEMENTAL INFORMATION DISCLOSURE CITATION
(Substitute PTO-1449)

This SUPPLEMENTAL INFORMATION DISCLOSURE CITATION is being submitted **prior to an action on the merits.**

NO FEE IS REQUIRED.

Charge any shortfall to Dep. Acct. 12-1445.

This SUPPLEMENTAL INFORMATION DISCLOSURE CITATION (5) is being provided in addition to:

- (1) INFORMATION DISCLOSURE CITATION, filed 4/4/96
- (2) SUPPLEMENTAL INFORMATION DISCLOSURE CITATION, filed 4/4/96
- (3) SUPPLEMENTAL INFORMATION DISCLOSURE CITATION, filed 4/4/96
- (4) SUPPLEMENTAL INFORMATION DISCLOSURE CITATION, filed 4/4/96

Although not required, TITLES for the patent references are provided herewith, as an aid to the examiner.

This SUPPLEMENTAL INFORMATION DISCLOSURE CITATION lists references cited in the International Search Reports pertaining to various commonly-owned, copending PCT applications. All the references listed in the Search Reports are listed herein. However, if the references have previously been disclosed, only the patent number is listed.

This SUPPLEMENTAL INFORMATION DISCLOSURE CITATION also lists references which recently have come to the applicant's attention.

The references presented herein are arranged in "groups", as follows:

GROUP 1. These references were cited in the International Search Report pertaining to commonly-owned, copending **PCT/US95/14909** filed **13 Nov 95**.

___ copies of these references are enclosed herewith, except for copies of references previously submitted to the Patent Office;

x copies of these references are NOT enclosed herewith, but have (i) previously been disclosed or (ii) may be found in the file of commonly-owned, copending U.S. Patent Application No. **08/452,255**, filed **5/26/95**

GROUP 2. These references were cited in the International Search Report pertaining to commonly-owned, copending **PCT/US95/14843** filed **13 Nov 95**.

___ copies of these references are enclosed herewith, except for copies of references previously submitted to the Patent Office;

x copies of these references are NOT enclosed herewith, but have (i) previously been disclosed or (ii) may be found in the file of commonly-owned, copending U.S. Patent Application No. **08/526,246**, filed **9/21/95**

GROUP 3. These references were cited in the International Search Report pertaining to commonly-owned, copending **PCT/US95/14842** filed **13 Nov 95**.

___ copies of these references are enclosed herewith, except for copies of references previously submitted to the Patent Office;

x copies of these references are NOT enclosed herewith, but have (i) previously been disclosed or (ii) may be found in the file of commonly-owned, copending U.S. Patent Application No. **08/533,584**, filed **10/18/95**

GROUP 4. References related to making pressure connections and resilient contact structures. These references were cited in the International Search Report pertaining to commonly-owned, copending **PCT/US95/14844** filed **13 Nov 95**.

x copies of these references are enclosed herewith, except for copies of references previously submitted to the Patent Office;

___ copies of these references are NOT enclosed herewith,

but have (i) previously been disclosed or (ii) may be found in the file of commonly-owned, copending U.S. Patent Application No. 08/554,902, filed 11/9/95

GROUP 5. References related to making pressure connections and resilient contact structures. These references were cited in the International Search Report pertaining to commonly-owned, copending PCT/US95/14885 filed 15 Nov 95.

___ copies of these references are enclosed herewith, except for copies of references previously submitted to the Patent Office;

x copies of these references are NOT enclosed herewith, but have (i) previously been disclosed or (ii) may be found in the file of commonly-owned, copending U.S. Patent Application No. 08/558,332, filed 11/15/95

GROUP 6. References which recently have come to the attention of the applicant.

___ copies of these references are enclosed herewith.

x copies of these references are NOT enclosed herewith, but may be found in the file of commonly-owned, copending U.S. Patent Application No. 08/340,144, filed 11/15/94

SHOULD THE EXAMINER DESIRE COPIES OF ANY REFERENCES CITED HEREIN, OR IN PREVIOUS INFORMATION DISCLOSURE CITATIONS, APPLICANT WILL PROVIDE SAME UPON REQUEST.

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GROUP 1: PCT/US95/14909 filed 13 Nov 95

<u>5,037,023</u>	<u>Akiyama, et al.; 8/91</u>	<u>228/102</u>
METHOD AND APPARATUS FOR WIREBONDING		
<u>5,210,939</u>	<u>Mallik, et al.; 5/93</u>	<u>29/840</u>
LEAD GRID ARRAY INTEGRATED CIRCUIT		
<u>4,659,437</u>	<u>Shiba, et al.; 4/87</u>	<u>204/28</u>
METHOD OF THERMAL DIFFUSION ALLOY PLATING FOR STEEL WIRE ON CONTINUOUS BASIS		
<u>5,309,324</u>	<u>Hernandez, et al.; 5/94</u>	<u>361/734</u>
DEVICE FOR INTERCONNECTING INTEGRATED CIRCUIT PACKAGES TO CIRCUIT BOARDS		

5,045,975 Cray, et al.; 9/91 361/412
THREE DIMENSIONALLY INTERCONNECTED MODULE ASSEMBLY

3,753,665 McCary, et al.; 8/73 29/191.6
MAGNETIC FILM PLATED WIRE

3,844,909 McCary, et al.; 10/74 204/40
MAGNETIC FILM PLATED WIRE AND SUBSTRATES THEREFOR

4,998,885 Beaman; 3/91 439/66
ELASTOMERIC AREA ARRAY INTERPOSER

JAP 3-142847 (64-279696); 10/89
SEMICONDUCTOR INTEGRATED CIRCUIT DEVICE

5,067,007	previously disclosed to PTO
5,110,032	previously disclosed to PTO
5,189,507	previously disclosed to PTO
5,317,479	previously disclosed to PTO
4,295,700	previously disclosed to PTO
4,764,848	previously disclosed to PTO
3,842,189	previously disclosed to PTO
4,667,219	previously disclosed to PTO
4,793,814	previously disclosed to PTO
4,751,199	previously disclosed to PTO
4,732,313	previously disclosed to PTO

GROUP 2: PCT/US95/14843 filed 13 Nov 95

5,386,344	previously disclosed to PTO
5,366,380	previously disclosed to PTO
5,317,479	previously disclosed to PTO
5,299,939	previously disclosed to PTO
5,189,507	previously disclosed to PTO
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5,095,187	previously disclosed to PTO
5,086,337	previously disclosed to PTO
5,067,007	previously disclosed to PTO
4,989,069	previously disclosed to PTO
4,955,523	previously disclosed to PTO
4,914,814	previously disclosed to PTO
4,893,172	previously disclosed to PTO
4,860,433	previously disclosed to PTO
4,821,148	previously disclosed to PTO
4,793,814	previously disclosed to PTO
4,777,564	previously disclosed to PTO
4,764,848	previously disclosed to PTO
4,705,205	previously disclosed to PTO
4,667,219	previously disclosed to PTO

4,642,889	previously disclosed to PTO
4,532,152	previously disclosed to PTO
4,418,857	previously disclosed to PTO
4,330,165	previously disclosed to PTO
4,295,700	previously disclosed to PTO
4,067,104	previously disclosed to PTO
3,795,037	previously disclosed to PTO
3,616,532	previously disclosed to PTO
3,509,270	previously disclosed to PTO
3,460,238	previously disclosed to PTO
3,373,481	previously disclosed to PTO

GROUP 3: PCT/US95/14842 filed 13 Nov 95

<u>5,045,975</u>	<u>Cray, et al.; 9/91</u>	<u>361/412</u>
THREE DIMENSIONALLY INTERCONNECTED MODULE ASSEMBLY		

5,317,479	previously disclosed to PTO
5,189,507	previously disclosed to PTO
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4,893,172	previously disclosed to PTO
4,860,433	previously disclosed to PTO
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4,705,205	previously disclosed to PTO
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4,418,857	previously disclosed to PTO
4,074,342	previously disclosed to PTO
3,616,532	previously disclosed to PTO

GROUP 4: PCT/US95/14844 filed 13 Nov 95

<u>5,187,020</u>	<u>Kwon, et al.; 2/93</u>	<u>428/601</u>
COMPLIANT CONTACT PAD		

<u>4,983,907</u>	<u>Crowley; 1/91</u>	<u>324/158 P</u>
DRIVEN GUARD PROBE CARD		

<u>5,148,103</u>	<u>Pasiecznik, Jr.; 9/92</u>	<u>324/158 P</u>
APPARATUS FOR TESTING INTEGRATED CIRCUITS		

<u>5,471,151</u>	<u>DiFrancesco; 11/95</u>	<u>324/757</u>
ELECTRICAL INTERCONNECT USING PARTICLE ENHANCED JOINING OF METAL SURFACES		

<u>3,832,632</u>	<u>Ardezzone; 8/74</u>	<u>324/158 P</u>
MULTI-POINT PROBE HEAD ASSEMBLY		

GROUP 5: PCT/US95/14885 filed 15 Nov 95

4,983,907 Crowley; 1/91 324/158 P
DRIVEN GUARD PROBE CARD

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PROBE PLATE USED FOR TESTING A SEMICONDUCTOR DEVICE, AND A
TEST APPARATUS THEREFOR

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COMPLIANT CONTACT PAD

GROUP 6: Other References of Interest

5,525,545 Grube, et al.; 6/96 437/209
SEMICONDUCTOR CHIP ASSEMBLIES AND COMPONENTS WITH PRESSURE
CONTACTS

5,518,964 DiStefano, et al.; 5/96 437/209
MICROELECTRONIC MOUNTING WITH MULTIPLE LEAD DEFORMATION AND
BONDING

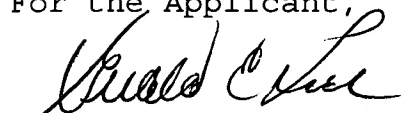
5,491,302 DiStefano, et al.; 2/96 114/260
MICROELECTRONIC BONDING WITH LEAD MOTION

5,489,749 DiStefano, et al.; 2/96 174/261
SEMICONDUCTOR CONNECTION COMPONENTS AND METHOD WITH RELEASABLE
LEAD SUPPORT

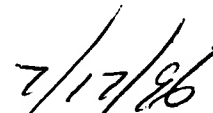
5,477,611 Sweis, et al.; 12/95 29/840
METHOD OF FORMING INTERFACE BETWEEN DIE AND CHIP CARRIER

5,455,390 DiStefano, et al.; 10/95 174/262
MICROELECTRONICS UNIT MOUNTING WITH MULTIPLE LEAD BONDING

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date

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